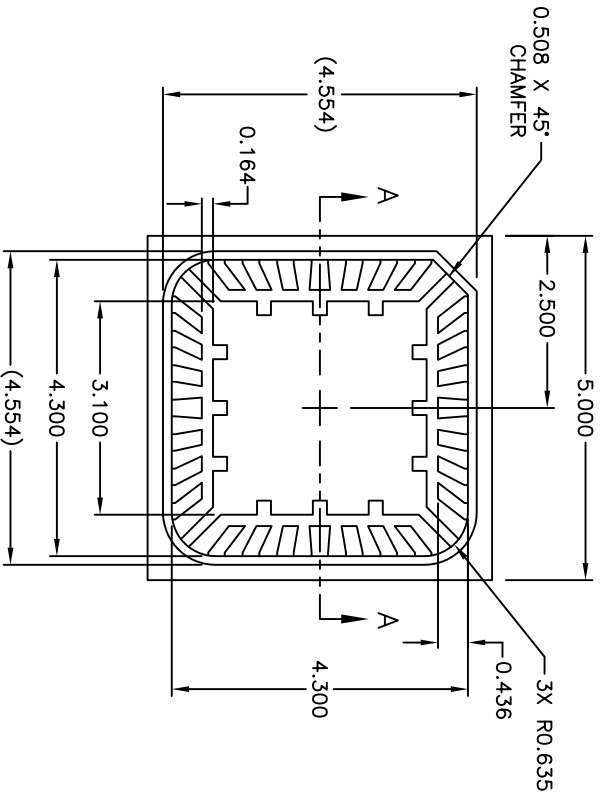


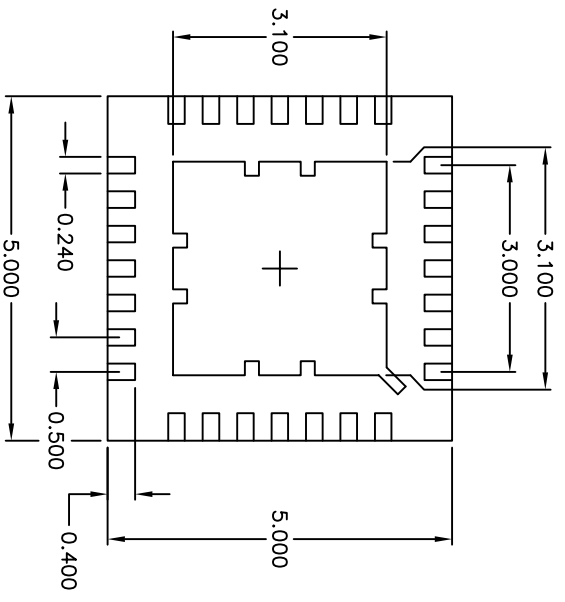
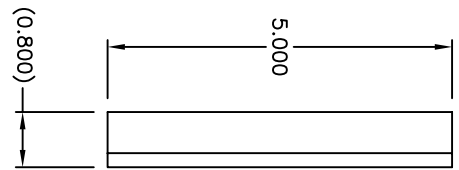
2

1

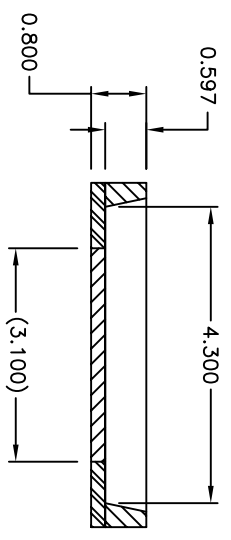
REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	
10493	10/27/05	PRODUCTION RELEASE	D.BENANDIO



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  2. LEAD FRAME: COPPER, 194 FH.
  3. LEAD FINISH: FULL GOLD PLATE.
  4. FRAME THICKNESS: 0.2030 ±.0076.
  5. DIE PAD: 3.100 X 3.100.
  6. JEDEC OUTLINE: MO-220 (VHHD-3).



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: XXXX ± 0.15 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	07/26/05
APP BY	P. FLASKERUD	DATE	07/28/05
CUSTOMER	---		

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28 Lead 5.00mm x 5.00mm  
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP5X5-28-0P-01	1
SCALE	NONE	
FILE	MLP5X5-28-0P-01-R1.DWG	
SHEET	1 OF 1	

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